

## FEATURES

- 90 Watts Peak Pulse Power per Line (tp=8/20μs)
- Ultra Low Capacitance: 0.3pF(typ.)
- Working voltages : 8 V
- Low Clamping Voltage

## APPLICATIONS

- Cellular Handsets and Accessories
- Display Ports
- MDDI Ports
- USB Ports
- Digital Visual Interface (DVI)
- PCI Express and Serial SATA Ports



DFN1006



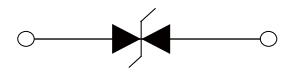
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## IEC COMPATIBILITY

- IEC61000-4-2 (ESD) ±25kV (air), ±20kV (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)

## APPROVALS

- RoHS** Compliance with 2011/65/EU
- HF** Compliance with IEC61249-2-21:2003



Schematic Symbol

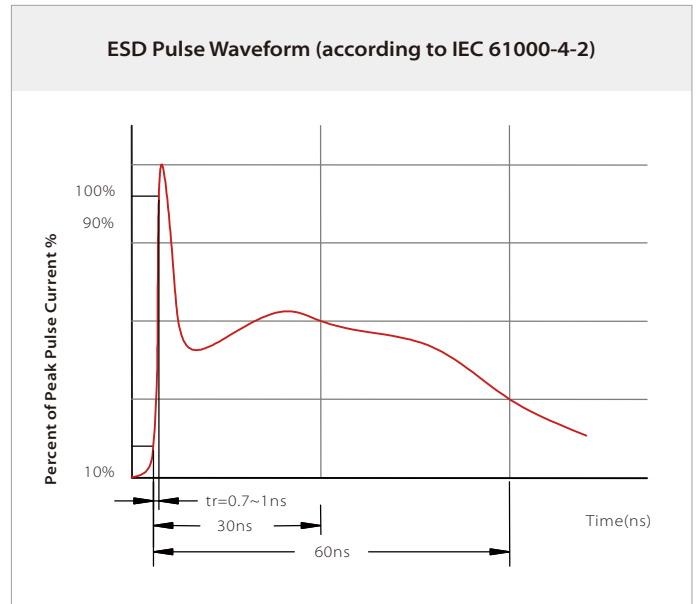
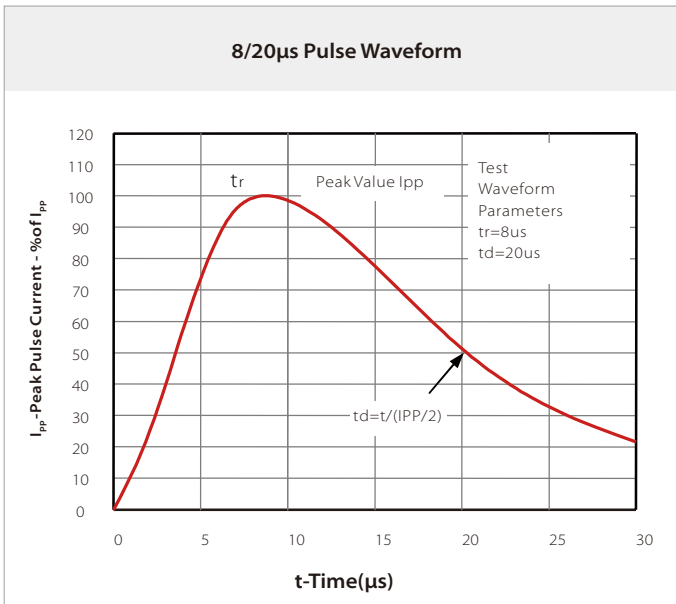
## THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
$P_{PP}$	Peak Pulse Power (tp=8/20μs waveform)	90	Watts
$T_J$	Operating Temperature Range	-55 to +125	°C
$T_{STG}$	Storage Temperature Range	-55 to +150	°C

## ELECTRICAL CHARACTERISTICS

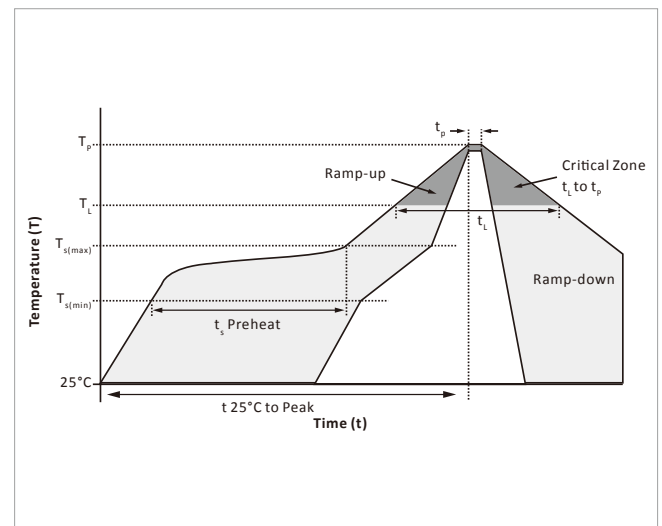
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
$V_{RWM}$	Reverse Stand-off Voltage				8	V
$V_{BR}$	Reverse Breakdown Voltage	$I_T=1mA$	8.5			V
$I_R$	Reverse Leakage Current	$V_{RWM}=8V$			0.2	μA
$V_C$	Clamping Voltage (Tp=8/20us)	$I_{pp}=1A, tp=8/20us$			15	V
$V_C$	Clamping Voltage (Tp=8/20us)	$I_{pp}=3.5A, tp=8/20us$			26	V
$I_{pp}$	Peak Pulse Current (Tp=8/20us)	tp=8/20us			3.5	A
$C_J$	Off State Junction Capacitance	$V_R=0V, f=1MHz$		0.3		pF

## CHARACTERISTIC CURVES

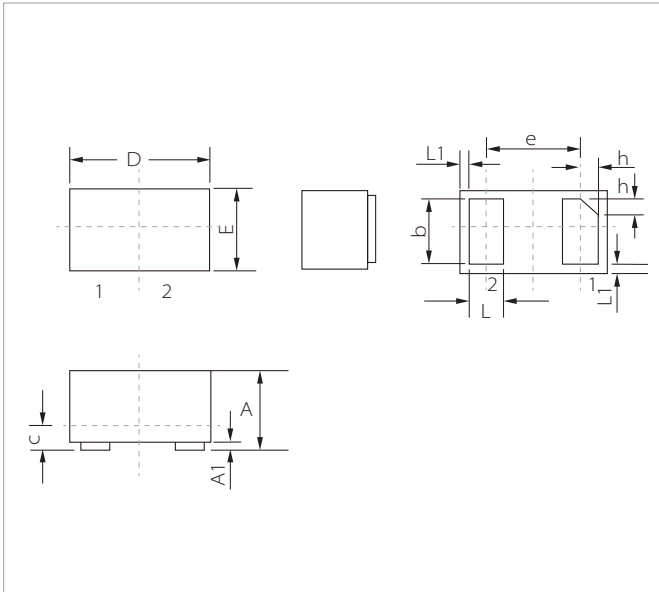


## SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ( $T_{s(min)}$ )	150°C
	Temperature Max ( $T_{s(max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (min to max) ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C

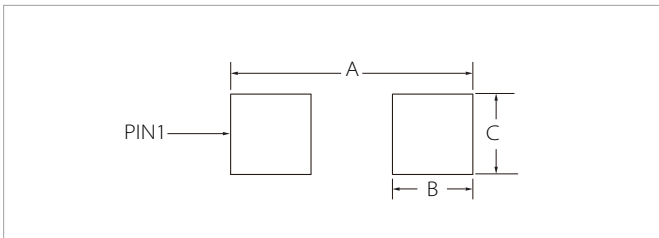


## DFN1006 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.35	0.50	0.014	0.020
A1	0	0.05	0	0.002
b	0.40	0.55	0.016	0.022
c	0.12	0.18	0.005	0.007
D	0.95	1.05	0.037	0.041
e	0.65BSC		0.026BSC	
E	0.55	0.70	0.022	0.027
L	0.20	0.35	0.008	0.014
L1	0.05REF		0.002REF	
h	0.07	0.17	0.003	0.007

## RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
A	1.20	0.047
B	0.47	0.019
C	0.60	0.024

## ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE10F10B8.0MA	DFN1006	10000PCS	7"

**Headquarters**

No.3387 Shendu Road Pujiang  
I&E Park  
Minhang Shanghai China  
201000

**Hotline**

400-021-5756

**Web**

<https://www.semiware.com>

**Sales Center**

Tel: 86-21-3463-7458  
Email: [sales18@semiware.com](mailto:sales18@semiware.com)

**Customer Service**

Tel: 86-21-5484-1001  
Email: [sales17@semiware.com](mailto:sales17@semiware.com)

**Technical Support**

Tel: 86-21-3463-7654  
Email: [fae01@semiware.com](mailto:fae01@semiware.com)

**Complaint & Suggestions**

Tel: 86-21-3463-7172  
Ext: 8868  
Email: [cs03@semiware.com](mailto:cs03@semiware.com)

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